

# Wafer cutting service

ISOM Science and Technology Service within the framework of the field of processing techniques research.





## Contact information

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## Technological Offers type

[Technological scientific services](#)

## Research and innovation areas

- [Industry, Materials and Circular Economy](#)

## ODS



**Available from:** 2015

## Where?

[ISOM Semiconductor Devices Group University Optoelectronics and Microtechnology Systems Institute](#)

Keywords: | [disc cutter](#) | [processing techniques](#)

## Diamond disc cutter

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### Description of the services offered

Silicon, or other material, wafer cutting into different pieces with the geometry desired by ISOM's technicians.

Training external clients to use the cutter. The possibility of cutting their own samples.

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### Needs requested and applications

The use of an entire wafer is not necessary to optimise production processes. The wafer can be divided into more manageable pieces with the desired geometry using the cutter.

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**Sector or area of application**

Electronics, optics, optoelectronics

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**Differential skills**

It is a professional cutter with numerical control that enables precise cuts to be made, even with sizes of only a few millimetres.

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**Previous references for provision of services****Where it is**

ISOM. HTSE for Telecommunications

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**Request for service**

[Protocolo de Acceso](#)

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